- cutting the rigid block laterally along the stacked assembly to expose ends of the conductive tracks at a common alignment level and so that the exposed ends are flush with a surface of one face of the block, which cutting step is performed at least once, and

- creating connections on the one face of the block with which the exposed ends are flush to interconnect the conductive tracks selectively and to connect the conductive tracks to connection means external to the module.

Claim 2. (Amended) The method claimed in claim 1 wherein at least one end of the stacked assembly has one or more supplementary modular printed circuit film elements which carry components and which have conductive tracks which terminate at a level corresponding to the common alignment level of the modular printed circuit film elements of said stacked assembly that carry the sets of turns of the one or more conductive tracks in order to perform the molding, cutting and connection creation steps simultaneously on the stacked assembly, including the one or more supplementary modular printed circuit film elements which carry components.

Claim 3 (Amended) The method claimed in claim 1 wherein at least one orifice is formed in the same position in each of the modular printed circuit film elements to form a conduit in the stacked assembly enabling a core to be inserted through said stacked assembly.

Please add the following new claims:

Claim 8. (New) A method of obtaining a module, comprising the steps of:

providing a first support and a second support;

forming at least a first conductive track having turns on the first support to form a winding thereon, wherein the first conductive track terminates at or near an edge of the first support;

forming at least a second conductive track having turns on the second support to form a winding thereon, wherein the second conductive track terminates at or near an edge of the second support;

stacking the first support on top of the second support to form a stacked assembly;

molding an insulative material over the stacked assembly to form a block;

cutting the block laterally along the stacked assembly to expose respective ends of the first and second conductive tracks at a common alignment level and so that the exposed ends are flush with one face of the block; and

interconnecting the conductive track elements on the one face of the block.

Claim 9. (New) The method claimed in claim 8, further comprising the steps of:

providing a supplementary support that carries an electrical component and that has a conductive track terminating at or near an edge of the first supplementary support;

prior to molding the insulative material over the stacked assembly to form a block, stacking the supplementary support with the first support and the second support so that the stacked assembly includes the supplementary support, the first support, and the second support, and so that the step of cutting the block laterally along the stacked assembly exposes respective ends of the conductive tracks on the supplementary support, the first conductive tracks and the second conductive tracks at a common alignment level and so that the respective exposed ends are flush with one face of the block.

Claim 10 (New) The method claimed in claim 8, wherein at least one orifice is formed in the same position in each of first and second supports to form a conduit in the stacked assembly enabling a core to be inserted through the stacked assembly.

Claim 11. (New) The method claimed in claim 8, wherein in the steps of forming the first and second conductive tracks, the first conductive track is formed so that the first conductive track terminates at the edge of the first support, and the second conductive track is formed so that the second conductive track terminates at the edge of the second support before performing the stacking step.